

# **Inductors**

Transponder coils Size  $11.4 \times 3.5 \times 2.4$  (mm)

Series/Type: B82450A\*A

Date: October 2008



## Transponder coils

B82450A\*A

#### Size $11.4 \times 3.5 \times 2.4$ (mm)

**SMD** 

# Rated inductance 1 mH to 7 mH Sensitivity 16 to 51 mV/μT



#### Construction

- Ferrite core
- Winding: enamel copper wire welded to terminals
- Flame-retardant molding

#### **Features**

- Robust construction for a high mechanical stability when exposed to shock, drop and bending tests
- Qualified to AEC-Q200
- High sensitivity
- Suitable for pick and place and AOI (Automatic Optical Inspection)
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020C
- RoHS-compatible

#### **Applications**

- Car access systems
  - immobilizer
  - PEPS (Passive Entry, Passive Start)
- TPMS (Tire Pressure Monitoring Systems)

#### **Terminals**

- Base material CuSn6
- Layer composition Ni, Sn (lead-free)
- Electro-plated

#### Marking

- Marking on component: Manufacturer, L value (nH, coded), letter "A", date of manufacture (YWWD), last five digits of lot number, internal information
- Minimum data on reel: Manufacturer, ordering code, L value, quantity, date of packing

#### Delivery mode and packing unit

- 24-mm blister tape, wound on 330-mm Ø reel
- Packing unit: 2500 pcs./reel



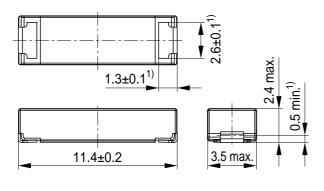
Transponder coils

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# Dimensional drawing and layout recommendation



8.4 12.2

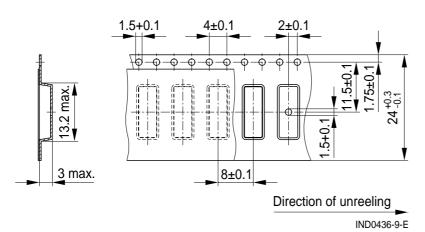
1) Soldering area

IND0636-Q-E

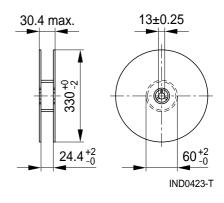
Dimensions in mm

# Taping and packing

Blister tape



Reel



Dimensions in mm



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# Technical data and measuring conditions

Rated inductance L <sub>R</sub>	Measured with Agilent 4294A and test fixture Agilent 16034 at frequency f <sub>L</sub> , RMS voltage 500 mV, 20 °C				
Q factor Q <sub>min</sub>	Measured with Agilent 4294A and test fixture Agilent 16034 at frequency f <sub>Q</sub> , RMS voltage 500 mV, 20 °C				
Sensitivity S <sub>typ</sub>	Measured with Helmholtz coil test setup at 125 kHz				
Resonance frequency f <sub>res</sub>	Measuring with network analyzer Agilent 8753D, 20 °C				
DC resistance R <sub>max</sub>	Measured at 20 °C				
Solderability (lead-free)	Sn95.5Ag3.8Cu0.7: $(245 \pm 5)$ °C, 3 s Wetting of soldering area $\geq 90\%$ (based on IEC 60068-2-58)				
Resistance to soldering heat	260 °C, 40 s (as referenced in JEDEC J-STD 020C)				
Climatic category	40/125/56 (to IEC 60068-1)				
Storage conditions	Mounted: -40 °C +125 °C Packaged: -25 °C +40 °C, ≤75% RH				
Weight	Approx. 0.32 g				

# **Characteristics and ordering codes**

L <sub>R</sub>	L tolerance	f <sub>L</sub> , f <sub>Q</sub>	Q <sub>min</sub>	S <sub>typ</sub> mV	R <sub>max</sub>	f <sub>res</sub>	Ordering code
mH		kHz		μT	Ω	MHz	
1.0	±3%	125	40	16	15	> 3.5	B82450A1004A000
2.36		125	50	30	25	> 2.0	B82450A2364A000
4.9		125	40	41	55	> 1.2	B82450A4904A000
7.0		125	40	51	85	> 1.1	B82450A7004A000

Characteristics and ordering codes for other L values available on request.



### **Cautions and warnings**

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  - Particular attention should be paid to the derating curves given there.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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